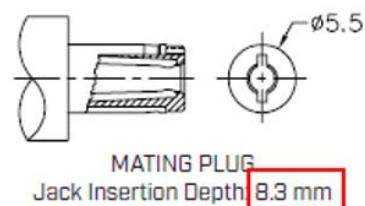
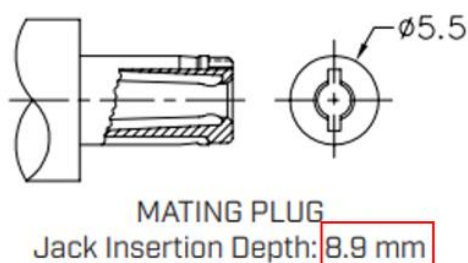
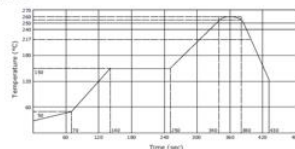
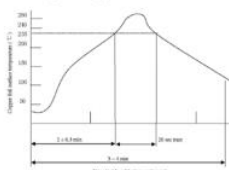
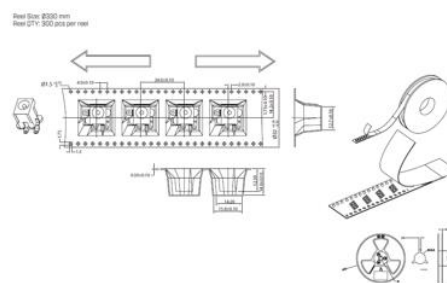
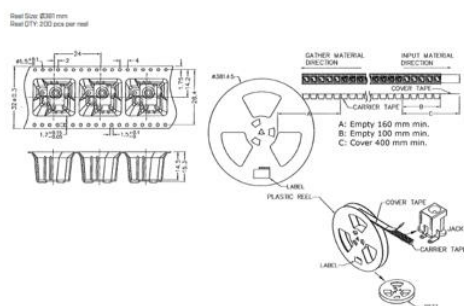


PREVIOUS CUI DEVICES DETAIL / IMAGE			NEW CUI DEVICES DETAIL / IMAGE		
	MATERIAL	PLATING		MATERIAL	PLATING/COLOR
center pin	brass	nickel	center pin	brass	nickel
terminal 1	brass	silver	terminal 1	brass	silver
terminal 2	copper alloy	silver	terminal 2	bronze	silver
terminal 3	brass	silver	terminal 3	brass	silver
plastic	PA6T or equivalent		housing	LCP (UL94V-0)	black
			cover	PA9T (UL94V-0)	black



PREVIOUS CUI DEVICES DETAIL / IMAGE			NEW CUI DEVICES DETAIL / IMAGE																																																		
SOLDERABILITY <table border="1"> <thead> <tr> <th>parameter</th><th>conditions/description</th><th>min</th><th>typ</th><th>max</th><th>units</th></tr> </thead> <tbody> <tr> <td>reel storage</td><td>at relative humidity <60%</td><td></td><td>40</td><td></td><td>°C</td></tr> <tr> <td>reflow soldering¹</td><td>see reflow profile</td><td>255</td><td>260</td><td>265</td><td>°C</td></tr> <tr> <td>drying conditions²</td><td>parts in reel bake at 40°C ±5°C for 72 hours parts removed from reel bake at 40°C ±5°C for 10 hours</td><td></td><td></td><td></td><td></td></tr> </tbody> </table> Note: 1. Must reflow solder within 72 hours from opening vacuum packaging at a temperature <10°C relative humidity <60%. 2. When reflowing from 40°C to 100°C. 			parameter	conditions/description	min	typ	max	units	reel storage	at relative humidity <60%		40		°C	reflow soldering ¹	see reflow profile	255	260	265	°C	drying conditions ²	parts in reel bake at 40°C ±5°C for 72 hours parts removed from reel bake at 40°C ±5°C for 10 hours					SOLDERABILITY <table border="1"> <thead> <tr> <th>parameter</th><th>conditions/description</th><th>min</th><th>typ</th><th>max</th><th>units</th></tr> </thead> <tbody> <tr> <td>reel storage</td><td>±30°C, 30% humidity</td><td></td><td></td><td></td><td>°C</td></tr> <tr> <td>reflow soldering</td><td>see reflow profile</td><td></td><td>260</td><td></td><td>°C</td></tr> <tr> <td>drying conditions</td><td>parts in reel bake at 40±5°C for 72 hours parts removed from reel bake at 40±5°C for 10 hours</td><td></td><td></td><td></td><td></td></tr> </tbody> </table> Note: 1. CUI Devices recommends to solder within 72 hours from opening vacuum packaging at a temperature <10°C relative humidity <60%. 			parameter	conditions/description	min	typ	max	units	reel storage	±30°C, 30% humidity				°C	reflow soldering	see reflow profile		260		°C	drying conditions	parts in reel bake at 40±5°C for 72 hours parts removed from reel bake at 40±5°C for 10 hours				
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Affected Date Code: *04/18/2023*

Product Availability: *Pertaining to market availability*

PCN Approval:

Operations/Quality

A handwritten signature in black ink, appearing to read "Rae O'Brien", is written over a horizontal line.

Product Management

A handwritten signature in black ink, appearing to read "J. Chadsen", is written over a horizontal line.